



October 23th 2015 Room 201, National Taiwan University Hospital International Convention Center

# DUV-LEDs Development and Applications

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### **Presentation Outline**



### 1. Introduction

- Going to shorter wavelength
- ✓ UV-LED vs traditional UV Lamp

### 2. Development and Performance of DUV-LED

- ✓ Comparison InGaN-based LED / AIGaN-based LED
- Evolutions of DUV-LED performance: IQE, LEE, EE
- ✓ Characteristics of Commercial DUV-LED
- Next Generation DUV-LED

### 3. Applications for DUV-LED

- ✓ Module development
- ✓ Analysis Applications
- ✓ Disinfection Applications
- ✓ Market evolution

### 4. Conclusion

# Applications in UV Range





Below 300nm, large volume market for applications such as water, air or surface disinfection, and high added value market in medical or biochemical field

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# **UV Range and UV Sources**

- Ultraviolet Radiation Range (ISO standard: ISO-21348):
- √ 315nm~400nm···UVA
- ✓ 280nm~315nm···UVB
- √ 100nm~280nm\*\*\*UVC

### Sources of UV

### -UV-LED (Mercury, Deuterium, Xenon...) InGaN-based UV-LED ( >360 nm) AlGaN-based Deep UV (DUV) LED (<360nm) TO-46- can package wo/w lens AlGaN-based UV LED Emission Spectrum: 0.1 <u>a</u> 270nm 280nm Normalized Intensity 0 0 5 305nm 315nm 335nm Germicidal Lamps Deuterium Lamp www.GElighting.com Hearaus NobelLight HP 350 400 Wavelength [nm]

With their long history, traditional UV Light sources are well implanted and are able to deliver high output power but ...

# Advantages of UV-LED Systems



### Compare to traditional UV-Light Sources, UV-LED has significant Advantages:

- √ Shock resistant semiconductor
- ✓ Customizable emission wavelength
- ✓ Modulation of UV output power
- ✓ Easy integration (design flexibility, simple driving circuits, low voltage operation)
- ✓ Instant on/off => No warm-up/cool-down cycles, no shutter needed
- ✓ Diode lifetime in excess of 10,000 hours
- ✓ No mercury-filled UV bulbs
- √ No ozone production => No system exhaust



By the Minamata Convention on Mercury, regulation on mercury will be strict from 2020.

=> With their low environmental impact DUV-LEDs are expected to replace mercury lamps in many applications and to access to new markets thanks to their specificity.

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### From Blue to UV-LED



### New Technology Frontier Related to Nitrides



Prof. Akasaki, Meijo Univ.



Prof. Amano, Nagoya Uniy.

the 2014 Nobel Laureates in Physics



From blue LED to UV-LED Technology

Blue-LED

**UV-LED** 

1980 1990 2000 2010

### Background of Nikkiso's UV-LED Business



2006: UV Craftory, Nikkiso's subsidiary has been established as start-up company originating from UV-LED technology by professors Akasaki and Amano in Meijo University who are the 2014 Nobel winners in Physics.

**2012:** Nikkiso's UV-LED samples were supplied to some domestic customers.

**2013:** Nikkiso purchased the property (both land and buildings) for UV-LED mass production in Hakusan, Ishikawa, Japan.

2014: Hakusan factory achieved ISO9001:2008 for its quality management system.

**2015:** Starting Mass Production of 30 mW high power SMD product.



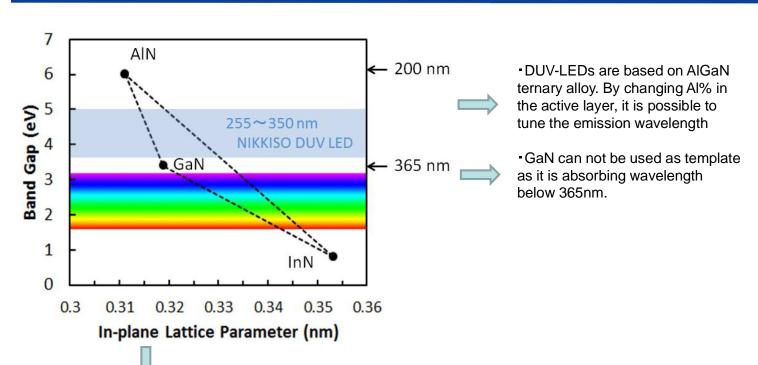


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# Band Gap and Emission Wavelength





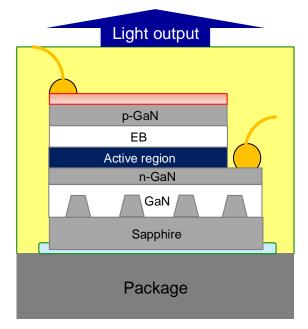
Even small difference in lattice parameter may induce stress, cracks, dislocations:

⇒ fine optimization of growth parameters is necessary to obtain devices with high crystal quality

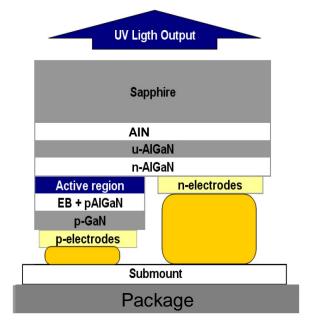
### **Device Structure Comparison**



### InGaN-based LED:



### AlGaN-based DUV-LED:



Compare to InGaN-based LED, DUV-LEDs have several constraints:

- ➤ Use of PSS substrate difficult for AlN/AlGaN growth
- High resistivity of AlGaN layers with high Al mole fraction
- Very low hole carrier concentration for p-type AlGaN
- Absorption of DUV light by pGaN layer
- ➤ No appropriate resin materials transparent and resistant to DUV light

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### **Performance Comparison**



Parameters	UV-LED	DUV-LED
	(InGaN-based)	(AlGaN-based)
IQE: Internal Quantum Efficiency	>80%	<80%
LEE: Light extraction Efficiency	>80%	<25%
EQE: External Quantum Efficiency	>80%	<15%
EE: Electrical Efficiency	>90%	<90%
WPE: Wall Plug Efficiency	>50%	<5%
Max Power /Chip	>5 W	< 100 mW
(Irradiance Working Distance >3mm)	( >16 W/cm <sup>2</sup> )	(<500 mW/cm <sup>2</sup> )
Lifetime and reliability	> 50000 hours	>10000 hours
Cost/ W	\$	\$\$\$\$

Best values are greatly depending on the measurement conditions and on the overall performance.

# IQE Optimization (1): AIN Template Fabrication



Template will affect the crystal quality, the Al mole fraction and the stress of the overgrowth AlGaN layer

Approach	Growth Method	Crystal quality	Growth Challenge	DUV LED EQE	Availability
AIN on Sapphire	-MEMOCVD -Pulse-flow -High Temp -HVPE	-DD~10 <sup>9</sup> cm <sup>-2</sup> -Smooth (DD: Dislocation Density)	Lattice mismatch, cracks	EQE 6.5% (>10% for improved LEE)	Up to 4 inch (demonstrated)
ELO AIN	-on Patterned Sa -on Patterned AIN	-DD<2x108cm <sup>-2</sup> -pits	Need regrowth, and thick layer, coalescence difficult	EQE 3%	Difficult for large diameter, Cost (need process, regrowth, thick growth)
Bulk AIN	-Sublimation -PVT	-DD<10 <sup>5</sup> cm <sup>-2</sup> -Smooth	UV Transparent Layer, Low Al% AlGaN regrowth	EQE 3% (270nm)	1 inch available (high cost), 2 inch (R&D stage)

- "High quality AIN is very difficult to grow due to a narrow growth window, strong parasitic reactions at elevated temperature" (Y. A. Xi APL89, 103106, 2006)
- At Nikkiso, we developed a stable growth process on Sa in order to have high quality, uniform and reproducible AIN template.

Growth of DUV-LED on sapphire remains the competitive approach

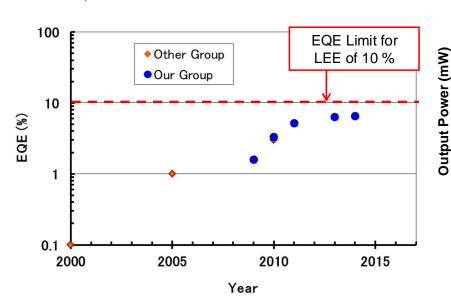
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# IQE Optimization(2): Device Structure



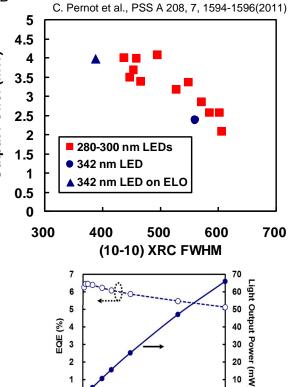
### **Evolution of EQE**

Bare chip measurement under same condition for 280-290nm LED



289nm bare chip (2013): EQE = 6.5% @ 10mA WPE = 5.0 % @ 10mA

Best EQE results obtained at low current => presence of droop at high current



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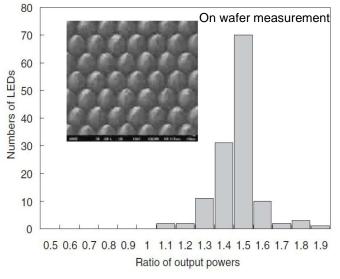
20 10

250

150 200 Current (mA)

# LEE Optimization (1): Surface Roughening





Numphase Stocking

1 um

C Pernot et al. Appl. Phys. Express 3 (2010) 061004

Inoue et al. Appl. Phys. Lett. 106, 131104 (2015)

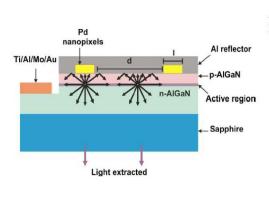
- Sapphire substrate with Moth-eye pattern on back side:
- →On wafer Improvement of Output Power by × 1.5
- Hybrid nano photonic pattern on back side of AIN substrate
- →Output Power×1.96 265nm LED with EQE of 6.3%

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# LEE Optimization(2): Reflective Electrodes





Al-based p-electrode
Reflectance > 80%

contact layer
< 10%

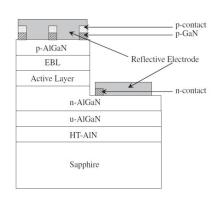
emission

n-AlGaN

AlN

Sapphire

LEE=30%



Lobo et al. Appl. Phys. Lett. 96, (2010) 081109

Akiba et al. PSS C, 9, (2012) 806

Inazu et al. J. J. Appl. Phys. 50 (2011) 122101

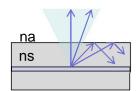
- •Nano pixels contacts (390nm LED) with high reflective electrodes Output Power x 1.9 (Vf increased by about 2V @100mA)
- Very thin p-GaN contact layer with high reflective electrodes
   p-GaN thickness < 10nm (>65% transmission) => Output Power x 1.2 (Vf not mentioned)
- •Mesh p-GaN contact layer with high reflective electrodes

  Output Power x 1.27 (x1.55 when combining with n-reflective electrodes).

  Voltage increase by 0.45V (20mA)
- => Trade-off between LEE improvement and Vf increase

# LEE Improvement (3): Encapsulation



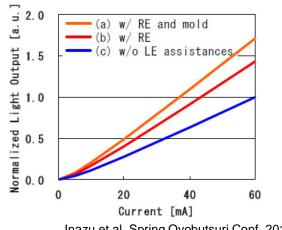


internal refractive critical angle:  $\alpha_c = n_a/n_s$  $\Rightarrow$  In case of Air/ Sapphire :  $\alpha_c = 33.7^{\circ}$  (@300nm)

To improve light extraction efficiency, resin for encapsulation is actively researched In addition to LEE, mechanical and electrical reliability can be improved

Resin materials should present:

- ✓ Good transparency to DUV radiation
- ✓ Low degradation when exposed to UV light
- ✓ Refractive index between Air and Sa (AIN)
- ✓ Good adherence to the chip
- ✓ Robustness to environment (not too soft)
- ✓ Half-ball shaping for efficient light extraction



Inazu et al. Spring Oyobutsuri Conf. 2011

LEE x 1.2 for 290nm LED on Sa (our group)

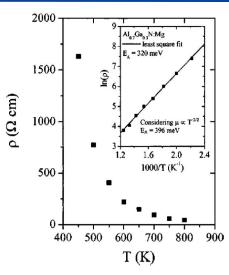
LEE x 2 for 270 nm LED on thinned AIN, J.R.Grandusky et al. APEX6 (2013) 032101

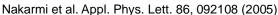
LEE x 1.35 for 278nm LED on Sa, M.Shatalov et al. APEX5 (2012) 082101

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# EE Improvement (1): p-AlGaN







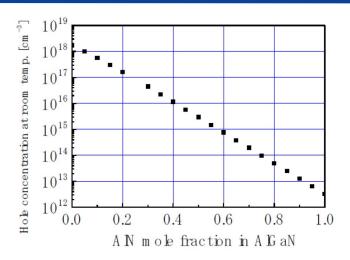


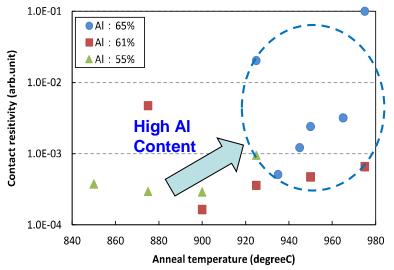
Fig. 8 Maximum hole concentration at room temperature in AlGaN. H. Amano et al. Proc. Of SPIE Vol. 7216 (2009)

- For Al mole fraction of 70%, activation energy of Mg acceptor is 320 meV.
- Hole carrier concentration decreases as the Al molar fraction increase in Mg-doped AlGaN layers.
- => Current DUV-LED devices are using thin pAlGaN layers for p-clad, and pGaN for contact layer.
- New dopants, short period super lattice, different semiconductors, new approach are under investigations for improving p-type layers.

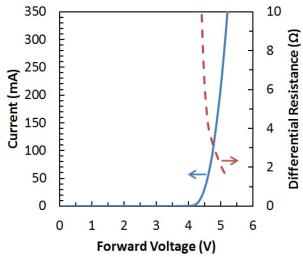
# EE Improvement (2): n-AlGaN







Forward current-voltage characteristics and differential resistance of a 285nm DUV-LED



- Inazu et al. Autumn Oyobutsuri Conf. 2015 Pernot et al. IEEE. 2015
- Optimization of n-contact annealing temperature is depending on AI mole fraction

Up to 70% AlGaN, n-type layers with sheet resistance below 60 Ω/□ can be fabricated

- As the Al mole fraction is increased the process window is becoming narrow

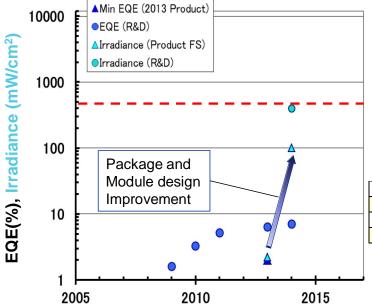
By optimizing every parameters, DUV-LED with low forward voltage can be obtained.

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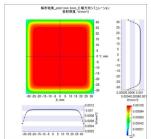
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# **Irradiance Optimization**





# High Density Packaging Array:



UV-LED 3.5x3.5mm2 SMD x 324pcs

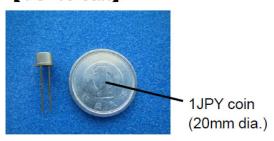
Peak Wavelength	Work Distance	Irradiance	Uniformity of irradiance
265nm	3mm	57mW/cm <sup>2</sup>	50mmsq
285nm	3mm	104mW/cm <sup>2</sup>	50mmsq
300nm	3mm	104mW/cm <sup>2</sup>	50mmsq

- To obtain high Irradiance DUV Module => high density array
- ⇒In addition to LED high and uniform output Power,
  Package/Module Thermal management and Vf uniformity are key
  parameters for high power applications

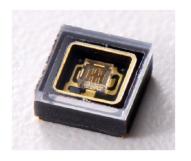
### **DUV-LED Products and Characteristics**



### [TO-46 can]



 $[3.5 \times 3.5 \text{ mm-sq SMD}]$ 



### standard TO-46 can

ltem		Unit	265nm	285nm	300nm
Forward current	I <sub>F</sub>	mA	15	20	20
Forward voltage	V <sub>F</sub>	V	5.0~7.0	4.5~6.0	4.5~6.0
Emission intensity	Po	mW	0.4	1.3	1.3
Peak wavelength	λ <sub>P</sub>	nm	265+/-5	285+/-5	300+/-5
Full width at half maximum	Δλ	nm	<15	<15	<20
Directional half power angle	<b>2</b> θ <sub>1/2</sub>	deg.	80	80	80

#### standard SMD

Item		Unit	265nm	285nm	300nm
Forward current	I <sub>F</sub>	mA	350	350	350
Forward voltage	V <sub>F</sub>	V	5.0~9.0	5.0~8.0	5.0~8.0
Emission intensity	Po	mW	>10	>25	>25
Peak wavelength	λ <sub>P</sub>	nm	265+/-5	285+/-5	300+/-5
Full width at half maximum	Δλ	nm	<13	<15	<17
Directional half power angle	<b>2</b> θ <sub>1/2</sub>	deg.	130	130	130

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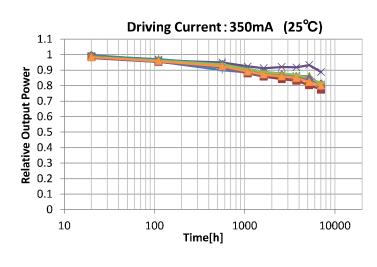
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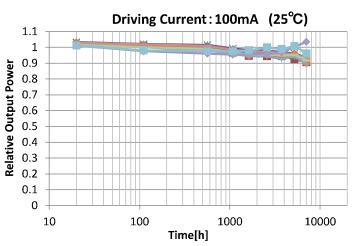
### **DUV-LED Lifetime**



Temperature and driving current are affecting lifetime of the DUV-LED device By growing high quality DUV-LED, lifetime over 10000 hours can be achieved.

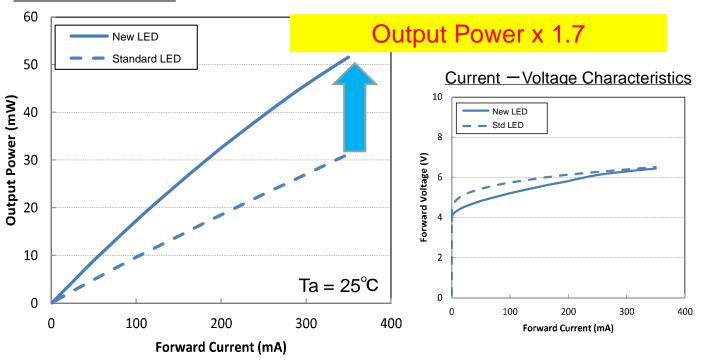
Output power evolution for 285 nm DUV-LED:







### I-L Characteristics



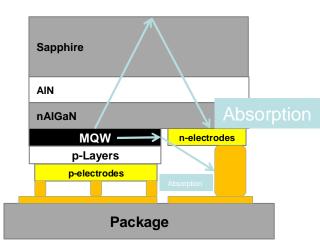
Achievement of 50 mW at 350mA driving current

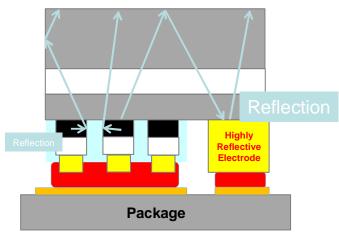
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# Optimization of Chip Light Extraction







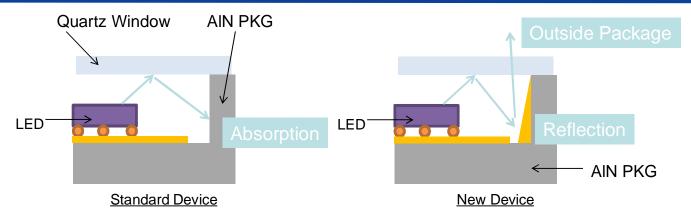
**Standard Device** 

**New Device** 

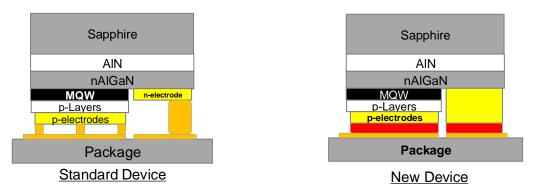
=> By inserting reflective surfaces on the back side of the chip (n-electrodes, mesa side area), it is possible to limit absorption, and to improve the light extraction of the device

# Optimization of Package





⇒ Improvement in Package Light extraction by using highly reflecting material and shape



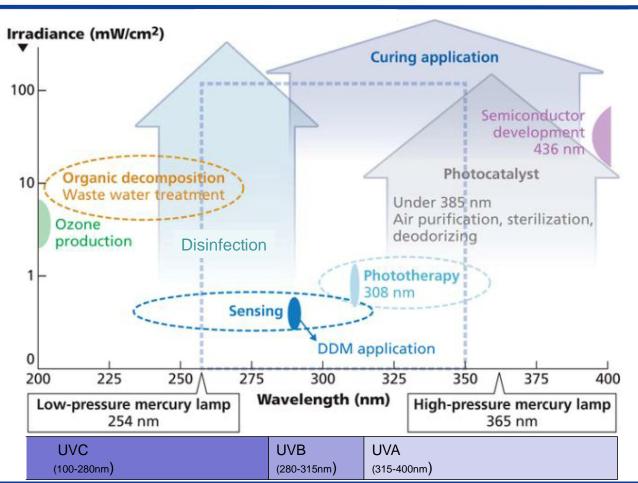
⇒ By increasing the contacting surface area between chip and package, the thermal resistance of the device is significantly decreased (15 K/W => 9 K/W)

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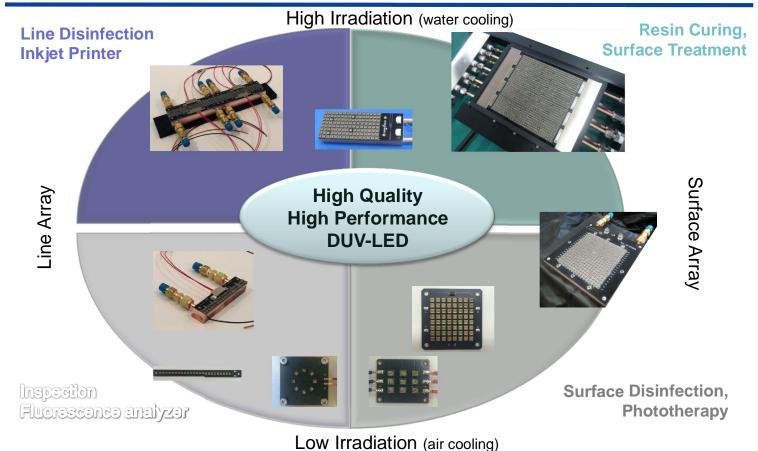
# **UV-LED Applications Map**





# Module Development





Depending on applications, development of optimized module solutions

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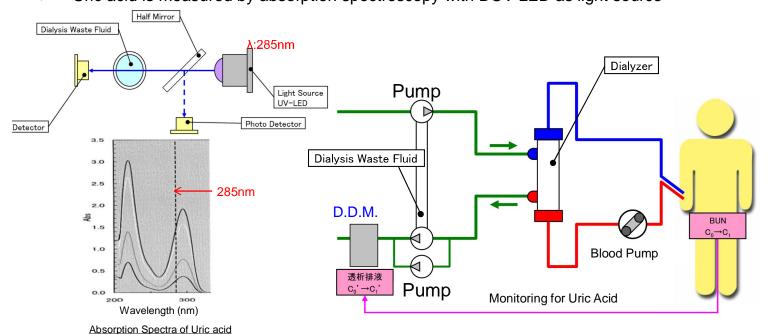
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# **UV-LED** for Sensing Application



### Example of Dialysis Dose Monitor (DDM)

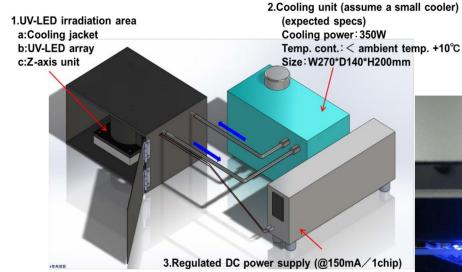
- Measurement of uric acid concentration contained in dialysis waste fluid
- Uric acid is measured by absorption spectroscopy with DUV-LED as light source



Other Potential Analysis applications include measurement of : Ozone, Protein, SO<sub>x</sub>, NO<sub>x</sub>, Chlorine, DNA/RNA, Oil, Bromic acid

# Module for Curing Applications





Customized modules designs based on customers needs are possible thanks to Nikkiso's know-how and simulation tools in optics, fluid dynamic and thermal analysis,



960 x 3.5mm-packages Irradiance of 80 mW/cm<sup>2</sup> at a working distance of 10 mm over an area of 25 x 25 cm<sup>2</sup>

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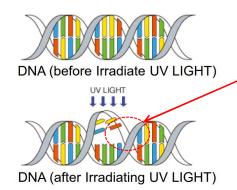
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# Disinfection by UV Light



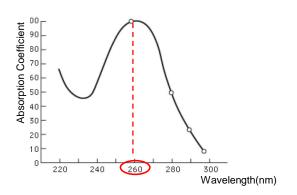
When living microorganisms such as bacteria are exposed to UV-C light between 250nm and 280nm (germicidal action spectra), their DNA can be effectively destroyed and inactivated by UVC; DNA cannot reproduce itself ⇒ Disinfection

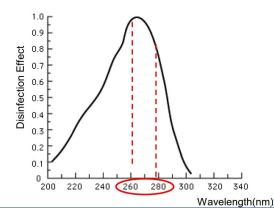
### **Principle**



DNA: Deoxyribonucleic Acid

DNA can be destroyed and inactivated by UV light irradiation.



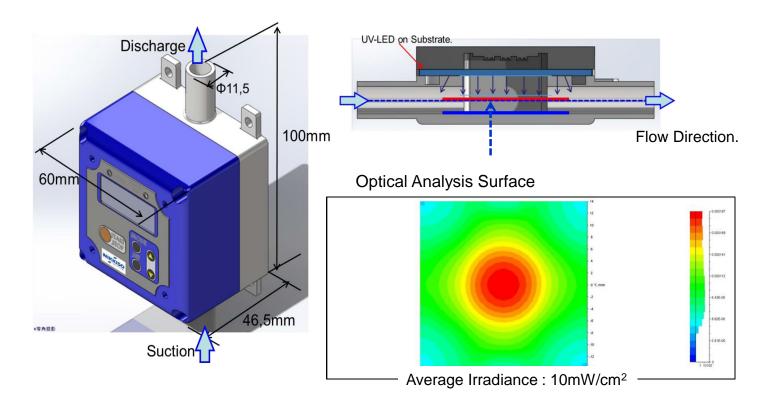


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### Prototype Module for Water Disinfection: Design





Product released in 2014

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# Prototype Module for Water Disinfection: Results



### <3x3 LED-array>

Irradiance (center area)

- > 40 mW/cm<sup>2</sup> (285 / 300 nm)
- > 15 mW/cm<sup>2</sup> (265 nm)

If = 350mA

Work distance: 10 mm Array size: 24 x 29 mm<sup>2</sup>





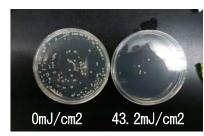
### Disinfection data for 10 mW/cm<sup>2</sup> (wavelength: 285 nm)

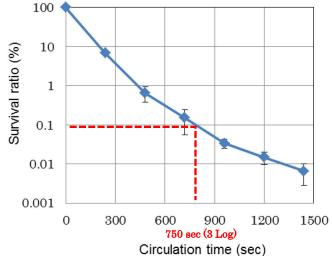
Initial number of bacteria: 10Million cfu/ml

(E. Coli : JCM1649)

Tank size: 1 LFlow rate: 2 L / min

Tests conducted at Japan Food Research Laboratories





### **New Modules for Water Disinfection**



### Low Flow Rate Type (2 L/min):

For integration in drinking water equipment and various systems



### Medium Flow Rate Type (10 L/min):

Home, hotel medium flow rate water disinfection



Specifications are subject to change without notice.

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# **New Modules for Water Disinfection**

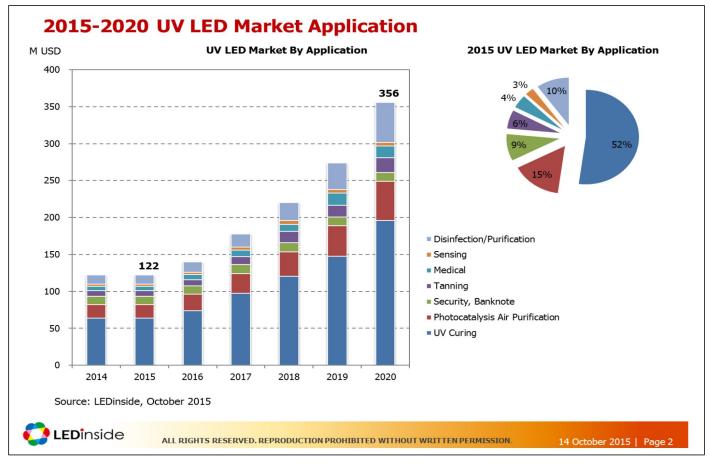


### ■ Specifications (Target)

lt	ltem Units 2L/min Type		10L/min Type	
Water	Fluid	-	Clear Water	Clear Water
	Density	-	1	1
	Viscosity	mPs•s	1	1
	Transparency	%/cm	Above 95%@280nm	Above 95%@280nm
Germicidal perf * Mortality of E.	ormance coli in rated flow	%	99.9%	99.9%
	Flow	L/min	2	10
	Pressure	MPa	0.5	0.5
Specificati	Current	mA	350	700
ons	Power	W	2.1	8.4
	Size	mm	Φ70 x L160	Φ110 x L215
	Weight	g	200	900
	Piping diameter	mm	Inlet:Φ14 Outlet:Φ14	Inlet: Ф19 Outlet: Ф14

Specifications are subject to change without notice.





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# Conclusion



- DUV-LED has some clear advantage compared with traditional UV light source
- After several years of continuous improvement, DUV-LED performance reached finally a level allowing industrial applications.
- For DUV-LED devices, thanks to recent improvement in
  - Electrodes design and process
  - · Chip and Package Light extraction
  - Device thermal management
  - ⇒ We achieve 285 nm DUV-LED with 50 mW Output Power at 350 mA
- For DUV-LED applications: to access the large potential markets, we are developing specific module solutions for each applications.
  - ⇒ For disinfection market, recent development include water disinfection modules with 99.9% germicidal performance in a single-pass for 2 to 10 L/min flow rate.

# Thank you for your attention!